ABSTRACT

Electroplating in instrument manufacture. The development of technological process for the deposition of copper conductive pattern on the printed circuit board assembly.

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Diploma project, 2015. Number of pages -125 and tables -32 , pictures - 6 , literature - 11 .

In the project the workflow galvanic deposition of copper coatings on conductive pattern of the printed circuit board assembly using sulfate electrolyte with additives such Grundeinebner Cupracid BL-CT and Glanzzusatz Cupracid BL is designed. This electrolyte is characterized by high scattering ability, uniform distribution of copper on the surface of the board, regardless of its size and picture conductors sedimentation of plastic, very strong layer with low internal tensions. For electroplating the six positional specialized galvanic bath of automatic line "Dina plus 130 " with a capacity of 160 000 PCB / year was selected and designed .

The project envisages measures for safety and automation of process parameters, the proposed method of sewage treatment by reagent method, followed by post-treatment galvanic-coagulation, the main technical and economic indicators were calculated.

Keywords : copper plating, current density, plating bath, a current source, print circuit board , sulfate electrolyte, the conductive drawing.